## ABSTRACT OF THE DISCLOSURE

A method for a quantitative evaluation of a substrate such as wafer defines a number of sequential first regions so that each of the first regions overlaps the adjacent region. A surface data (e.g., thickness data) in each of the first regions is used to determine a normal vector representing a surface configuration (e.g., thickness variation) of the first region. Then, an angular difference between the normal vectors is determined for each combination of adjacent two first regions. Subsequently, the determined angular difference is compared with a reference to evaluate a quality of a second region including at least one of the first regions, e.g., chip region, strip-like region and/or the entire of the wafer.